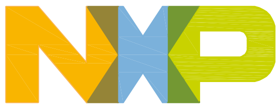

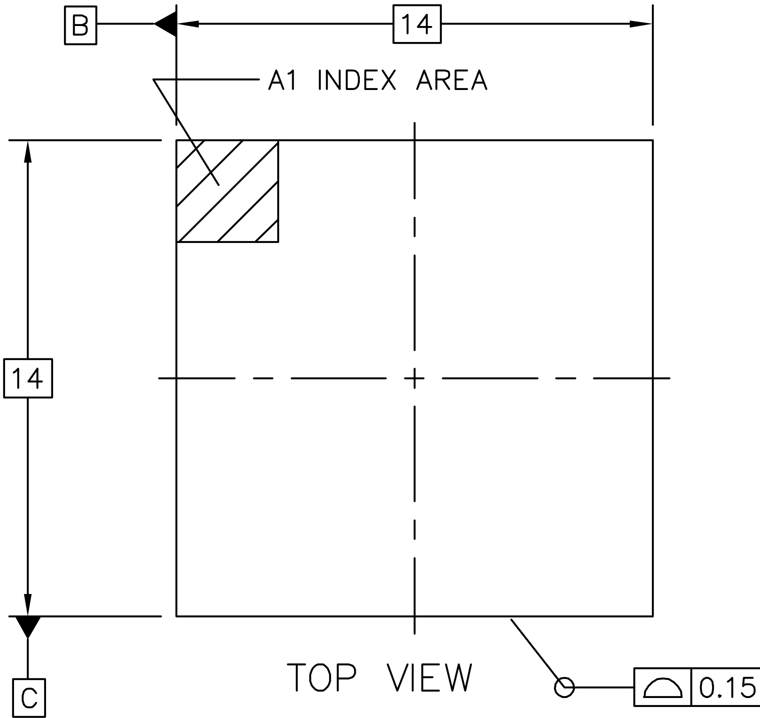

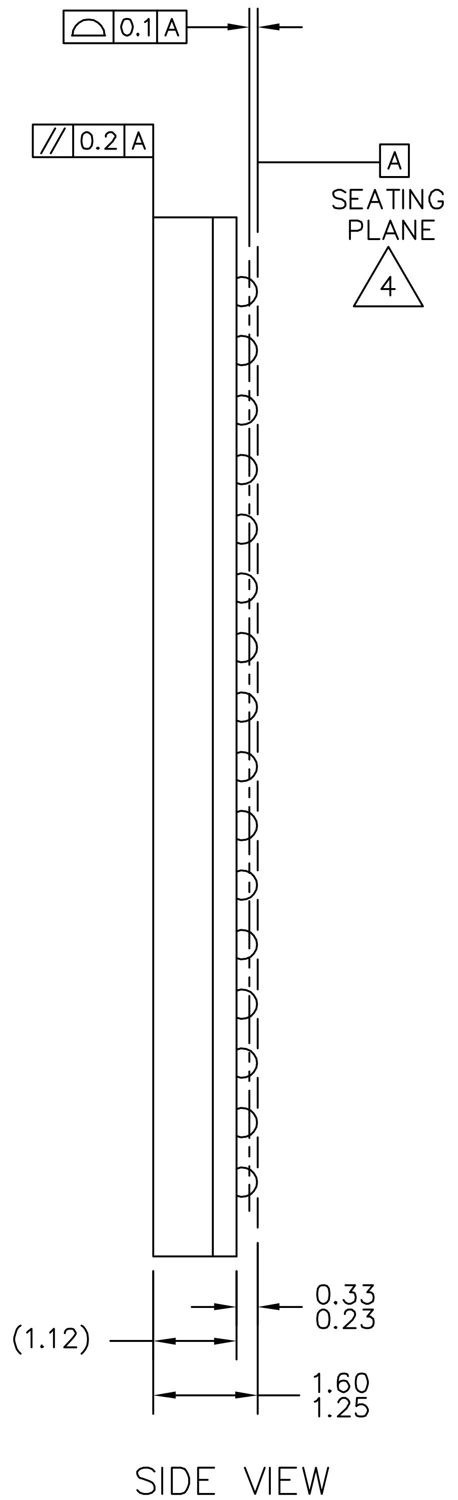

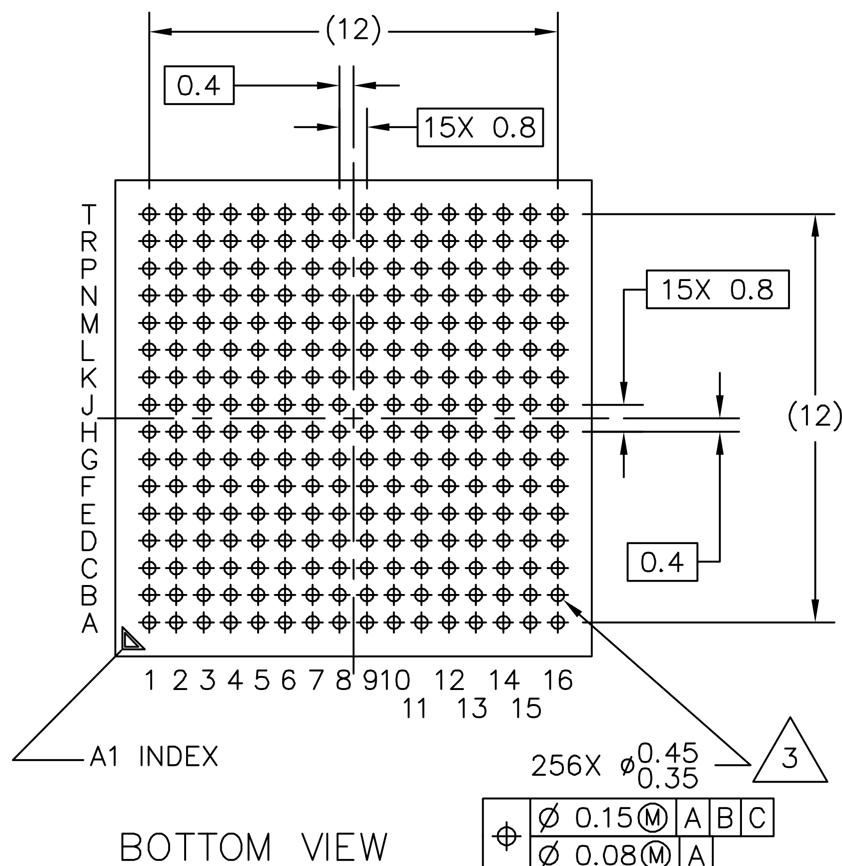

© NXP SEMICONDUCTORS N.V.
ALL RIGHTS RESERVED

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 256 I/O LOW PROFILE, FINE PITCH, PBGA, 14 X 14 PKG, 0.8 MM PITCH (STD MAP)	DOCUMENT NO: 98ASA99298D REV: B
	STANDARD: NON-JEDEC
	SOT1020-2 30 MAR 2016

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE IS DEFINED BY SPHERICAL CROWNS OF THE SOLDER BALLS.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 256 I/O LOW PROFILE, FINE PITCH, PBGA, 14 X 14 PKG, 0.8 PITCH (STD MAP)	DOCUMENT NO: 98ASA99298D REV: B
	STANDARD: NON-JEDEC
	SOT1020-2 30 MAR 2016